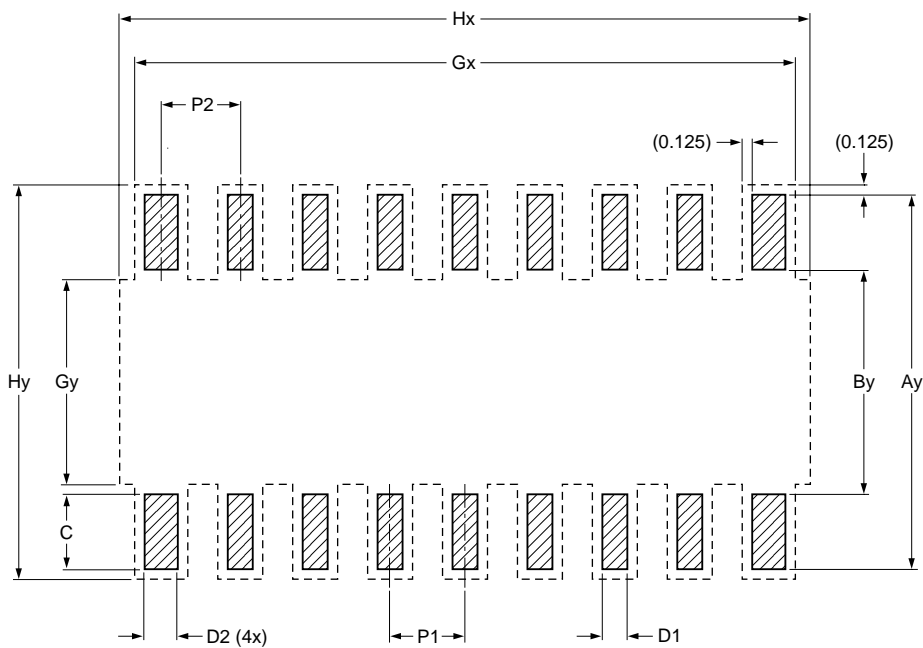




Footprint information for reflow soldering of TSSOP38 package

SOT510-1



Generic footprint pattern
Refer to the package outline drawing for actual layout

 solder land
 occupied area

DIMENSIONS in mm

P1	P2	Ay	By	C	D1	D2	Gx	Gy	Hx	Hy
0.500	0.560	7.200	4.500	1.350	0.280	0.400	9.770	5.300	10.500	7.450